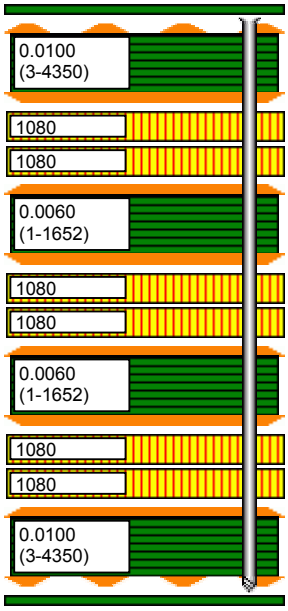
Building Tomorrow's Technology . . . Today

Customer : Texas Instruments
Part Num : DAC38J84
Part Rev :

Job Name : DAC38J84_RO4350
Engineer : David Gorden
Facility : Milpitas

Layer	Calc Thickness	Description
	0.0005	Taiyo 4000-BN
Layer - 1	0.0018	**1/2oz Sig (0.0012 Plt)**
	0.0100	R4350B
Layer - 2	0.0012	**1oz P/G**
	0.0058	370H
Layer - 3	0.0012	**1oz P/G**
	0.0060	370H
Layer - 4	0.0012	**1oz P/G**
	0.0058	370H
Layer - 5	0.0012	**1oz P/G**
	0.0060	370H
Layer - 6	0.0012	**1oz P/G**
	0.0058	370H
Layer - 7	0.0012	**1oz P/G**
	0.0100	R4350B
Layer - 8	0.0018	**1/2oz Sig (0.0012 Plt)**
	0.0005	Taiyo 4000-BN

Primary Stack



Requirement	Req. Thickness	Tol +	Tol -	Calc Thick
Incl. Plating & Mask	0.0620	0.0062	0.0062	0.0612
Incl. Mask over Laminate	0.0608	0.0061	0.0061	0.0576
Incl. Plating	0.0610	0.0061	0.0061	0.0602
After Lamination	0.0610	0.0031	0.0031	0.0578
Over Laminate	0.0598	0.0060	0.0060	0.0566

	Impedance Type	Layer	Design	Actual	Pitch	Plane	Target	Tol (ohms)	Predict
1	Surface MS	L1	0.01950	0.0200	-	-	50	5.0	50.00
		-	-	-	-	L2			
2	EC Microstrip	L1	0.00850	0.0095	0.0150	-	100	10.0	99.77
		-	0.00850	0.0095	-	L2			
3	Surface MS	L8	0.01950	0.0200	-	L7	50	5.0	50.00
		-	-	-	-	-			
4	EC Microstrip	L8	0.00850	0.0095	0.0150	L7	100	10.0	99.77
		-	0.00850	0.0095	-	-			